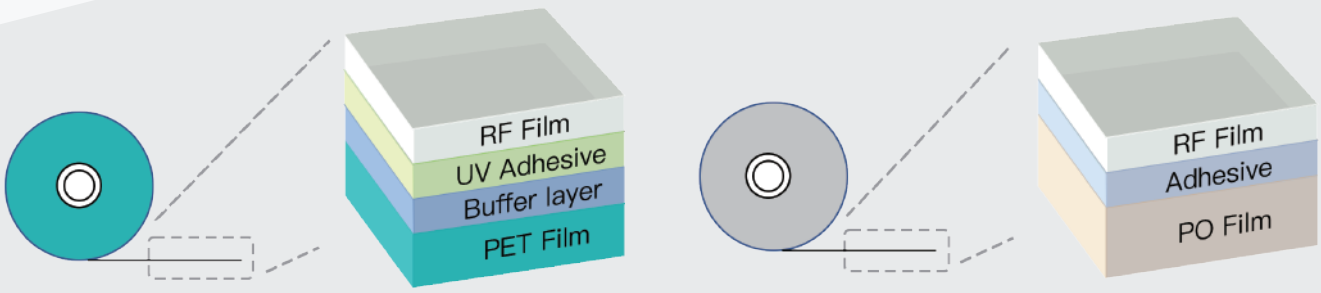
晶圓研磨膠帶 Wafer Back-Grinding Tape

適用於晶圓研磨製造的壓克力PET膠帶與壓克力PO膠帶，黏膠層由梯度堆疊組成，與晶圓接觸層具有高附著力，UV型膠帶有著對UV光敏感的特性，在 LED 365nm 曝光後附著力降低，可輕鬆去除。緩衝層具有高彈性模量和高蠕變性，可以消除晶圓片的翹曲、封裝晶圓片的凸塊。膠帶與晶圓服貼性良好，可防止研磨時的水滲透。

結構 / Structure



特性 / Features

- 黏膠層由模量梯度堆疊組成，緩衝層具有高彈性模量和高蠕變性。
- 良好的附著力，能防止水滲透，於膠帶撕除過程中不會殘膠在基材上。
- 黏膠具有穩定的高附著力，使用LED 365nm UV燈照射後附著力降低，易撕除。

規格 / Specification

產品名稱		UT165-SL	UT170-DL	Non UV NO205-BC
膠帶厚度		165	170	205
膠黏層厚度		60	120	40
黏著力 (gf/25mm)	紫外線曝前	1950	1300	室溫: 150
	紫外線曝後	20	20	50°C: 30
產品特色		薄型晶圓適用	凸塊晶圓適用	薄型晶圓適用
基材		PET	PET	PO

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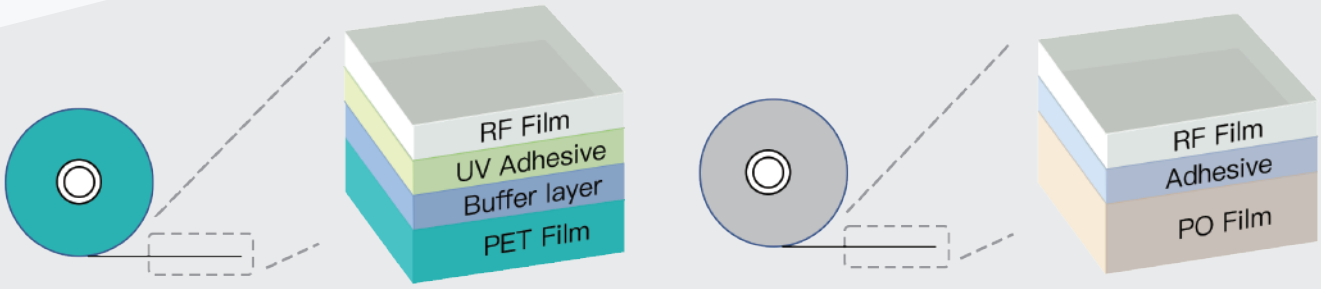
Wafer Back-Grinding Tape

The acrylic PET tape and PO tape is suitable for application in wafer back-grinding manufacture. The adhesive is composed of gradient stacking layers. The layer in contact with Si-wafer shows high adhesion, sensitive to UV-light and easily removable after exposure of 365nm LED. The buffer layer is high elastic modulus and high creep, which would eliminate the warpage of Si-wafer, encapsulate the bump of Si-wafer and preventing water infiltration.

Structure



Features

- Stable adhesion force and reduced adhesion after 365nm UV exposure.
- Excellent adhesion, no adhesive residue on substrate in the tape tear-off process.
- The adhesive is composed of modulus gradient layers and the buffer layer is high elastic modulus.

Specification

Product name		UT165-SL	UT170-DL	Non UV NO205-BC
Tape thickness		165	170	205
Adhesive thickness		60	120	40
180° peel force (gf/25mm)	Before UV	1950	1300	RT: 150
	After UV	20	20	50°C: 30
Features		Thin wafer	Wafer with bump	Thin wafer
Base film		PET	PET	PO

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